

Specifications



SMD Auto X8G HT150C Flex, Ceramic, 0.068 uF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 1812, 2.3 mm



General Information	
Series	SMD Auto X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade
Features	High Temperature, Ultra-Stable, Automotive Grade
RoHS	Yes
Termination	Flexible Termination
Marking	No
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	87 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1.6mm +/-0.20mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

••	0.2	
Т	1.6mm +/-0.20mm	
S	2.3mm MIN	
В	0.7mm +/-0.35mm	
Packaging Specifications		

Capacitance	0.068 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	2%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	14.7059 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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